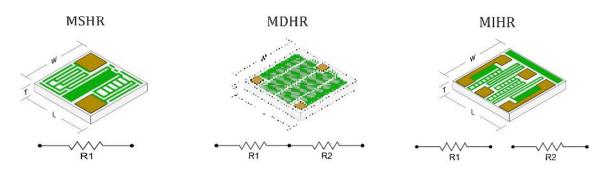
HIGH VALUE WIRE BONDABLE RESISTORS



Mini-Systems Inc. **High Value Wire Bondable Chip Resistor** series offers the design engineer a wide variety of styles with the **high stability** of Thin Film materials to meet the demands of cutting edge design requirements. Electrical connection to associated circuitry is accomplished through wire bonding to terminations located on the top side of the chip. Suitable die attachment methods are epoxy or eutectic attach.

GENERAL CHARACTERISTICS

Resistance Range	$301 \mathrm{k}\Omega$ to $100 \mathrm{M}\Omega^{\scriptscriptstyle 1}$
Resistance Tolerance	±0,1% to ±10%
Termination Material	Gold (Standard) Aluminum (Optional)
Termination Size	0.0035" Square Min Value Dependent
Backing Material	Bare Substrate (Standard) Gold (Optional)
Operating Temperature	-55°C to +150°C
Storage Temperature	-65°C to +150°C
Voltage Rating	100VDC Max

 $^{^{1}}$ Consult Engineering if higher valued resistors are required

SUBSTRATE CHARACTERISTICS

SUBSTRATE MATERIAL	Available Thickness	Dielectric Constant @ 1MHz	Thermal Conductivity W/m• K	
Silicon (Si) (with 12kÅ SiO ₂)	0.005" - 0.015"		149 (SiO ₂ 1.38)	
Quartz	0.005" - 0.010"	3.75	1.3	

RESISTOR CHARACTERISTICS

RESISTOR FILM	Passivation	Standard TCR	TCR Optional To	TCR Tracking	
SiChrome	SiO ₂	±150 ppm/°C	±100 ppm/°C	±5ppm/°C	

PART NUMBER DESIGNATION

MIHR -	- <u>3</u> -	SUBSTRATE	S RESISTOR FILM	30003¹ - 30003/40003² OHMIC VALUE	F TOLERANCE	- RN - RATIO ³	GB OPTION
MSHR MDHR MIHR	See Table	S = Silicon Q = Quartz	S = SiChrome	R1/R2 5-Digit Number: 1st 4 digits are significant with "R" as decimal point when required. 5th digit represents number of zeros.	$B = \pm 0.1\%$ $D = \pm 0.5\%$ $F = \pm 1\%$ $G = \pm 2\%$ $J = \pm 5\%$ $K = \pm 10\%$	RB = ±0.05% RC = ±0.10% RE = ±0.25% RD = ±0.50% RN = No Ratio	F = ±100ppm/°C E = Aluminum Pads G = Gold Bond Pads GB = Gold Back TR = Tape & Reel

EXAMPLE: MIHR-3-SS-30003/40003F-RN-GB

MIHR-3 Series, Silicon, SiChrome, $3M\Omega/4M\Omega$, $\pm 1\%$ Tol., No Ratio, Gold Backside

^{2,3} Use for dual resistors



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 $^{^{\}scriptscriptstyle 1}$ Use for single resistors

HIGH VALUE WIRE BONDABLE RESISTORS

HIGH VALUE WIRE BONDABLE CHIP RESISTORS

			DIMENSIONS			POWER RATING 1		
CASE SIZE	ТҮРЕ	L (±0.003") [±0.076mm]	W (±0.003") [±0.076mm]	T (±0.003") [±0.076mm]	RESISTANCE RANGE ²	Quartz	Si	
0101	101						50mW	
0201	21	0.020" [0.508]	0.010" [0.254]	0.006" [0.152]	451kΩ - 1.8MΩ	10mW	50mW	
0202	1						50mW	
0202	122	0.020" [0.508]	0.016" [0.406]	0.010" [0.254]	1.1ΜΩ - 2ΜΩ	25mW	125mW	
0202	2						250mW	
0302	32	0.030" [0.762]	0.020" [0.508]	0.010" [0.254]	2.1ΜΩ - 15ΜΩ	50mW	250mW	
0303	33						250mW	
0402	110	0.037" [0.940]	0.017" [0.432]	0.010" [0.254]	3.1ΜΩ - 20ΜΩ	25mW	125mW	
0404	35						250mW	
0404	4	0.040" [1.016]	0.040" [1.016]	0.010" [0.254]	11.1ΜΩ - 50ΜΩ	70mW	350mW	
0502	53						500mW	
0502	115	0.050" [1.270]	0.025" [0.635]	0.010" [0.254]	6.6ΜΩ - 45ΜΩ	50mW	250mW	
0505	112						500mW	
0603	63	0.060" [1.524]	0.030" [0.762]	0.010" [0.254]	11.1ΜΩ - 50ΜΩ	100mW	500mW	
0606	6						500mW	
0805	85	0.075" [1.905]	0.050" [1.270]	0.010" [0.254]	40.1ΜΩ - 100ΜΩ	100mW	500mW	

DUAL HIGH VALUE WIRE BONDABLE CHIP RESISTORS

	GA GE				DIMENSIONS			DEGLETA NOT	POWER RATING ¹ Per Resistor	
	CASE SIZE S'	STYLE	LAYOUT	VALUES	L (±0.003") [±0.076mm]	W (±0.003") [±0.076mm]	T (±0.003") [±0.076mm]	RESISTANCE RANGE ²	Quartz	Si
	0303	MDHR 3	Center Tapped	R1 ≤ R2	0,030" [0.762]	0 . 030" [0.762]	0,010" [0.254]	1.3MΩ - 15MΩ Per Res	25mW	125mW
	0303	MIHR 3	Isolated	R1 ≤ R2	0.030" [0.762]	0.030" [0.762]	0.010" [0.254]	1.3M Ω - 15M Ω Per Res	25mW	125mW
	0404	MDHR 4	Center Tapped	R1 ≤ R2	0.040" [1.016]	0.040" [1.016]	0.010" [0.254]	6.1M Ω - 25M Ω Per Res	25mW	125mW
	0404	MIHR 4	Isolated	R1 ≤ R2	0.040" [1.016]	0.040" [1.016]	0.010" [0.254]	6.1MΩ - 25MΩ Per Res	25mW	125mW

 $^{^{\}scriptscriptstyle 1}$ Power Rating at 70°C derated linearly to 0% at 150°C

All MSHR, MSDR, MIHR Series parts are produced on the same manufacturing line using the same materials and processes as parts manufactured to MIL-PRF-55342

¹ Power Rating at 70°C derated linearly to 0% at 150°C ² Consult Engineering if higher valued resistors are required

² Consult Engineering if higher valued resistors are required